

SURFACE MOUNT FAST RECOVERY RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Open Junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
250°C / 10 seconds at terminals
- ◆ Glass passivated chip junction

Mechanical Data

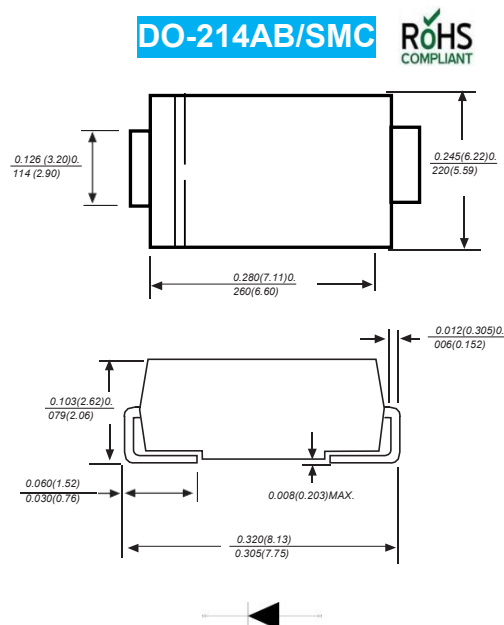
Case : JEDEC DO-214AB/SMC Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0077 ounce, 0.22grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	RCD RS5AC	RCD RS5BC	RCD RS5DC	RCD RS5GC	RCD RS5JC	RCD RS5KC	RCD RS5MC	UNITS
Marking Code									
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	I _(AV)	5.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	120							A
Maximum instantaneous forward voltage at 5.0A	V _F	1.30							V
Maximum DC reverse current TA=25℃ at rated DC blocking voltage TA=125℃	I _R	5 100							μA
Maximum reverse recovery time (NOTE 1)	t _{rr}	150				250	500		ns
Typical junction capacitance (NOTE 2)	C _J	50.0							pF
Typical thermal resistance (NOTE 3)	R _{θJA}	35.0							℃/W
	R _{θJC}	13.0							
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +150							℃

Note: 1. Reverse recovery condition $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
3. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

Fig.1 Forward Current Derating Curve

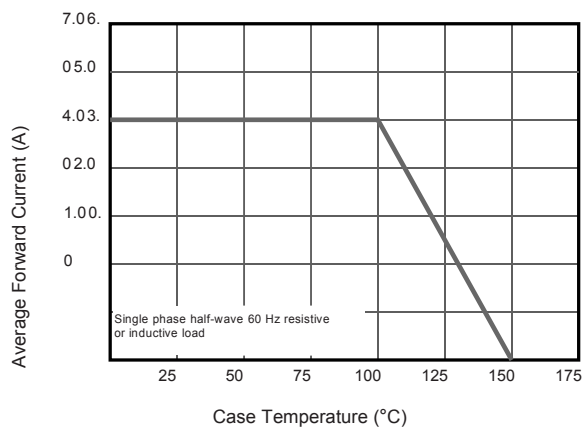


Fig.2 Typical Reverse Characteristics

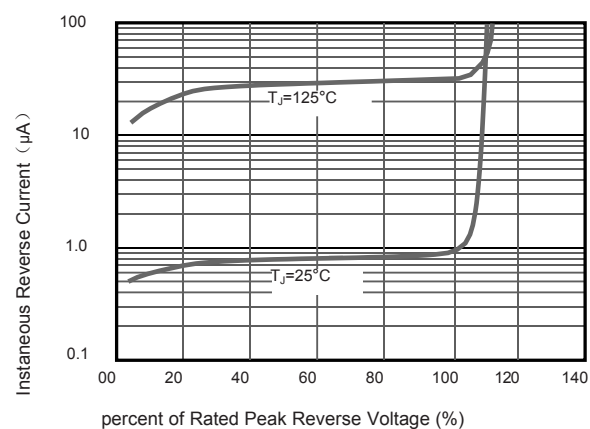


Fig.3 Typical Instantaneous Forward Characteristics Tj=25°C

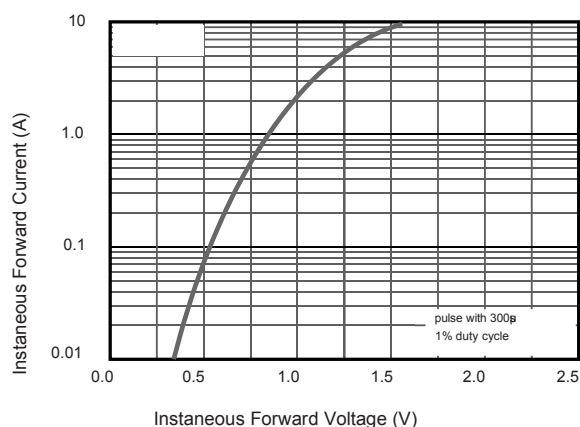


Fig.4 Typical Junction Capacitance

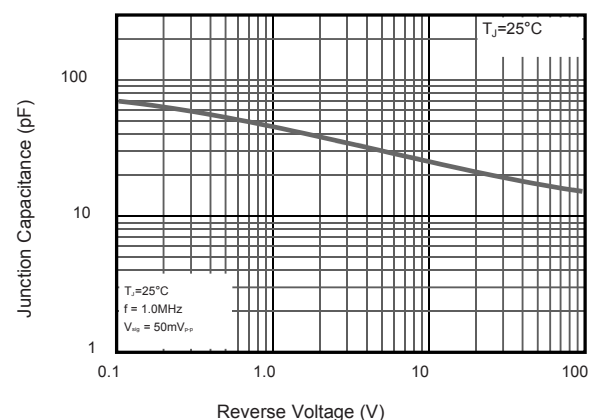
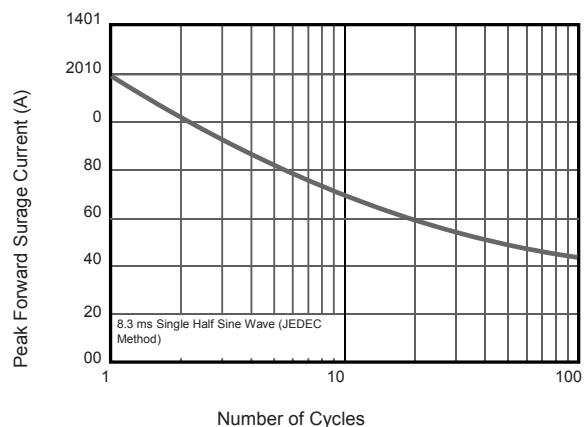
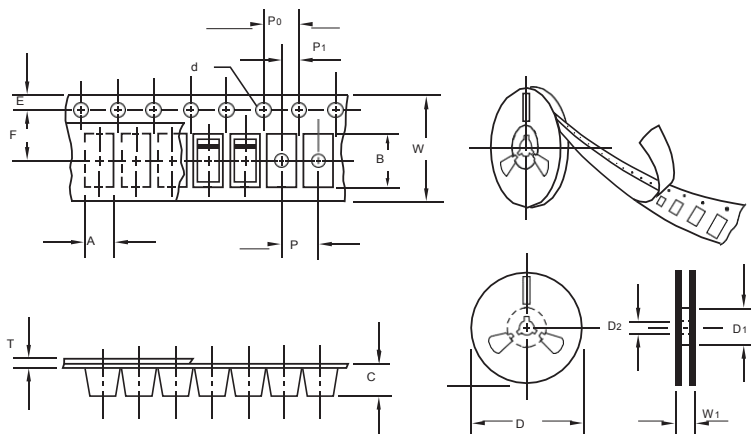


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



The curve above is for reference only.



unit:mm

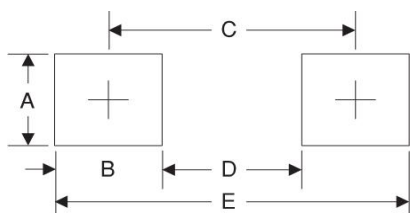
Item	Symbol	Tolerance	SMC
Carrier width	A	0.1	6.15
Carrier length	B	0.1	8.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	16.00
Reel width	W1	1.0	16.50

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMC	13"	3,000	4.0	6000	190*190*41	330	365*365*340	42000	14.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	4.3	0.170
B	4.1	0.160
C	7.9	0.311
D	3.8	0.150
E	12	0.472